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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10065632	FILING DATE 11/05/2002	CLASS 257	SUBCLASS 734	GAU 2814	EXAMINER <i>Eahy</i>
**APPLICANTS: Weng Chao-Fu;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: TAIWAN 91100094 01/07/2002					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 8012-US-PA	
TITLE : Chip structure with bumps and a process for fabricating the same					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
Amount Due Date Paid		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
		Application Examiner	
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